

3.2mmx1.6mm SMD CHIP LED LAMP

Features

- 3.2mmx1.6mm SMT LED, 0.75mm THICKNESS.
- LOW POWER CONSUMPTION.
- WIDE VIEWING ANGLE.
- IDEAL FOR BACKLIGHT AND INDICATOR.
- VARIOUS COLORS AND LENS TYPES AVAILABLE.
- PACKAGE : 2000PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 3.
- RoHS COMPLIANT.

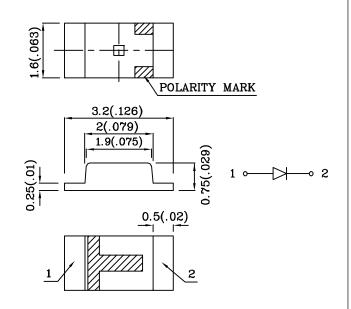




Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is \pm 0.2(0.008") unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Rating (TA=25°C)	UY (GaAsP/GaP)	Unit	
Reverse Voltage	VR	5	V
Forward Current	IF	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	iFS	140	mA
Power Dissipation	Рт	75	mW
Operating Temperature	TA	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	



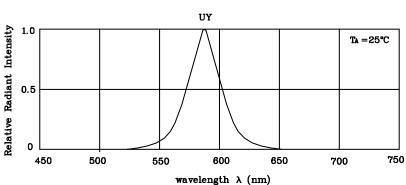
Operating Characteristics (Ta=25°C)		UY (GaAsP/GaP)	Unit
Forward Voltage (Typ.) (IF=20mA)	$V_{\rm F}$	2.1	V
Forward Voltage (Max.) (IF=20mA)	$V_{\rm F}$	2.5	V
Reverse Current (Max.) (VR=5V)	IR	10	uA
Wavelength of Peak Emission (Typ.) (IF=20mA)	λΡ	590	nm
Wavelength of Dominant Emission (Typ.) (IF=20mA)	λ D	588	nm
Spectral Line Full Width At Half-Maximum (Typ.) (IF=20mA)	Δλ	35	nm
Capacitance (Typ.) (VF=0V, f=1MHz)	С	20	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (IF=20mA) mcd		Wavelength nm λ P	Viewing Angle 2 θ 1/2
				min.	typ.		
XZUY55W-1	Yellow	GaAsP/GaP	Water Clear	2.6	7	590	120°
Published Date :	JAN 24, 2008	Drawing	g No : XDSA1328	V5	Checke	ed : B.L.LIU	P.1/4



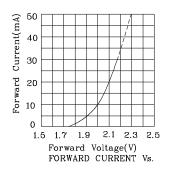
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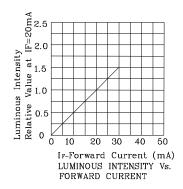


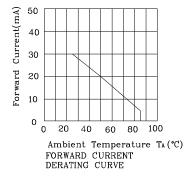


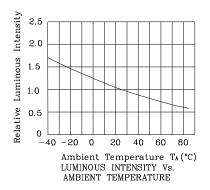
RELATIVE INTENSITY Vs. WAVELENGTH

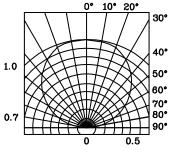
❖ UY









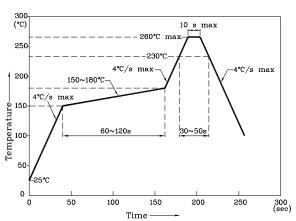


SPATIAL DISTRIBUTION

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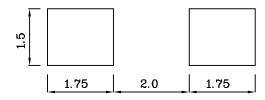
Reflow Soldering Profile For Lead-free SMT Process.

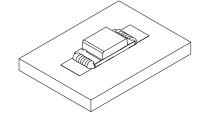
NOTES:

- 1. Maximum soldering temperature should not exceed 260°c.
- 2. Recommended reflow temperature: $145^{\circ}c-260^{\circ}c$.
- 3. Do not put stress to the epoxy resin during high temperatures conditions.

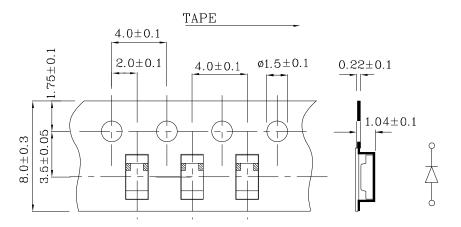
❖ Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)

❖ The device has a single mounting surface. The device must be mounted according to the specifications.





❖ Tape Specification (Units:mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous intensity / luminous flux: +/-15%
- 3. Forward Voltage: +/-0.1V

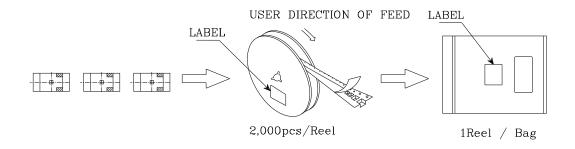
Note: Accuracy may depend on the sorting parameters.

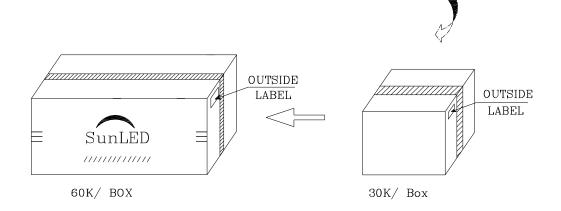


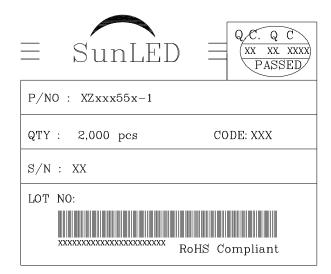
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PACKING & LABEL SPECIFICATIONS

XZUY55W-1







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